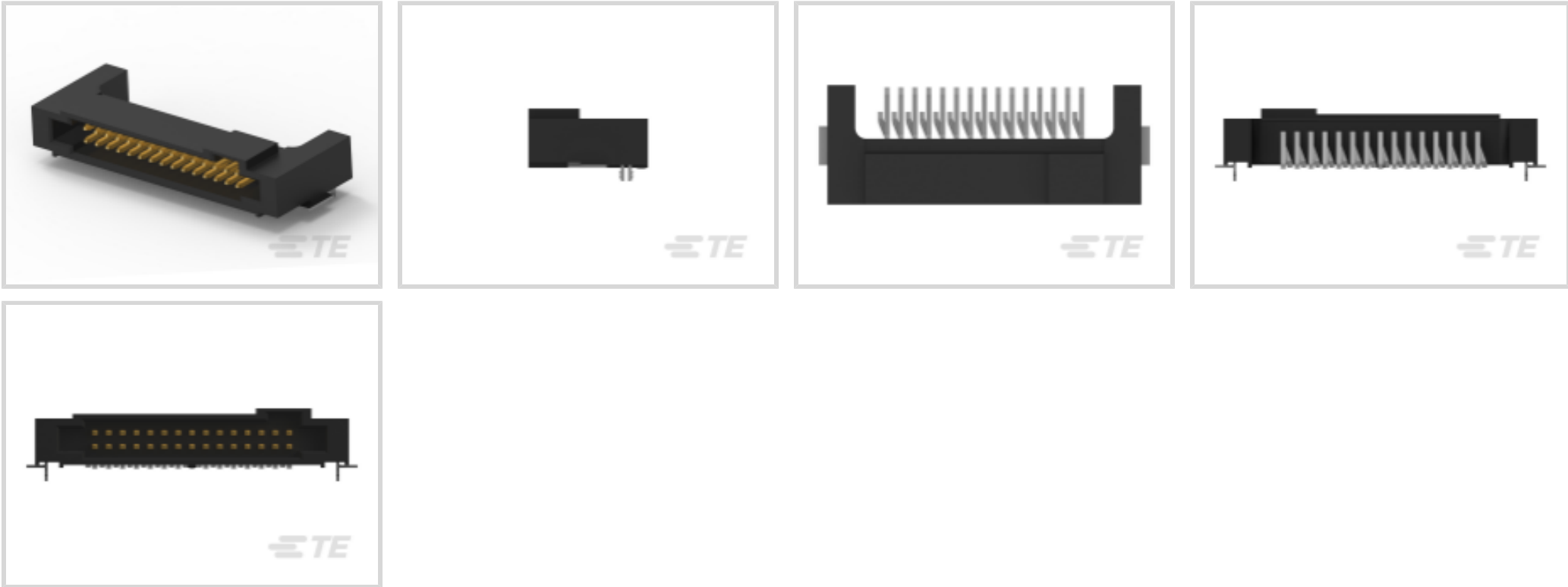




Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Right Angle**

Connector System: **Board-to-Board**

Number of Positions: **40**

Number of Rows: **2**

Features

Product Type Features

|                                   |                       |
|-----------------------------------|-----------------------|
| PCB Connector Assembly Type       | PCB Mount Header      |
| Connector System                  | Board-to-Board        |
| Header Type                       | Fully Shrouded        |
| Sealable                          | No                    |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

|                                  |              |
|----------------------------------|--------------|
| Connector Contact Load Condition | Fully Loaded |
| PCB Mount Orientation            | Right Angle  |
| Number of Positions              | 40           |
| Number of Rows                   | 2            |

Electrical Characteristics

|                                       |         |
|---------------------------------------|---------|
| Dielectric Withstanding Voltage (Max) | 300 VAC |
| Operating Voltage                     | 30 VAC  |

Body Features



|                                        |                 |
|----------------------------------------|-----------------|
| PCB Retention Feature Material         | Copper Alloy    |
| PCB Retention Feature Plating Material | Tin over Nickel |
| Connector Profile                      | Standard        |
| Primary Product Color                  | Black           |

Contact Features

|                                               |                 |
|-----------------------------------------------|-----------------|
|                                               | 150 µin         |
| Mating Pin Diameter                           | .46 mm[.018 in] |
| Contact Shape & Form                          | Square          |
| Contact Underplating Material                 | Nickel          |
| PCB Contact Termination Area Plating Material | Tin             |
| Contact Base Material                         | Brass           |
| Contact Mating Area Plating Material          | Gold            |
| Contact Type                                  | Pin             |
| Contact Current Rating (Max)                  | .5 A            |

Termination Features

|                                  |                 |
|----------------------------------|-----------------|
| Termination Post & Tail Diameter | .46 mm[.018 in] |
| Termination Method to PCB        | Surface Mount   |

Mechanical Attachment

|                          |                |
|--------------------------|----------------|
| PCB Mount Retention Type | Hold-Down Post |
| Mating Alignment         | With           |
| Mating Alignment Type    | Keyed          |
| PCB Mount Retention      | With           |

Housing Features

|                    |                 |
|--------------------|-----------------|
| Centerline (Pitch) | 1.27 mm[.05 in] |
| Housing Material   | Thermoplastic   |

Dimensions

|                    |                 |
|--------------------|-----------------|
| Row-to-Row Spacing | 1.27 mm[.05 in] |
|--------------------|-----------------|

Usage Conditions

|                             |              |
|-----------------------------|--------------|
| Operating Temperature Range | -65 – 105 °C |
|-----------------------------|--------------|

Operation/Application

|                        |                |
|------------------------|----------------|
| Solder Process Feature | Board Standoff |
|------------------------|----------------|



Industry Standards

|                                             |                       |
|---------------------------------------------|-----------------------|
| Compatible With Approved Standards Products | CSA LR7189, UL E28476 |
| UL Flammability Rating                      | UL 94V-0              |

Packaging Features

|                    |           |
|--------------------|-----------|
| Packaging Quantity | 14        |
| Packaging Method   | Box, Tube |

Product Compliance

For compliance documentation, visit the product page on [TE.com](#)>

|                                               |                                                                                                                                 |
|-----------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------|
| EU RoHS Directive 2011/65/EU                  | Compliant                                                                                                                       |
| EU ELV Directive 2000/53/EC                   | Compliant                                                                                                                       |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold                                                                                         |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JUNE 2024 (241)<br>Candidate List Declared Against: JUNE 2024 (241)<br>Does not contain REACH SVHC |
| Halogen Content                               | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free                                             |
| Solder Process Capability                     | Reflow solder capable to 260°C                                                                                                  |

Product Compliance Disclaimer

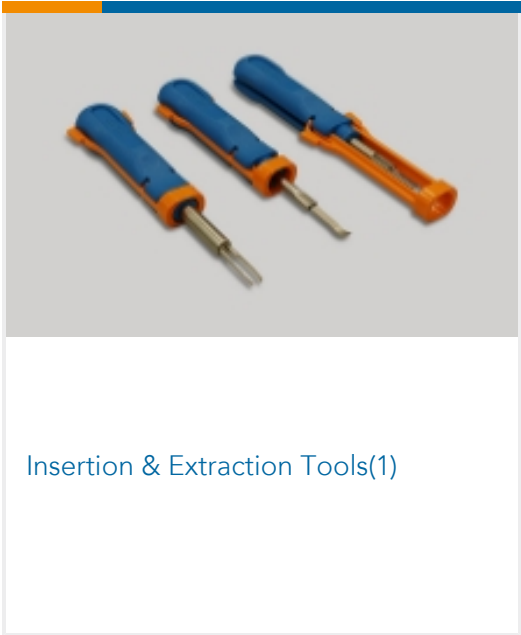
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) ‘Guidance on requirements for substances in articles’ posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

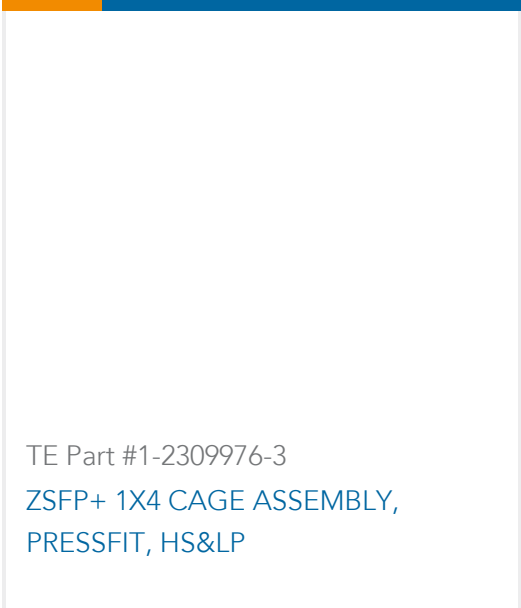
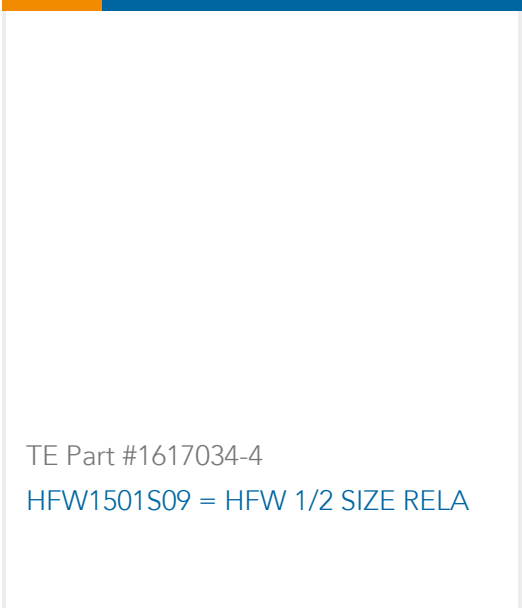
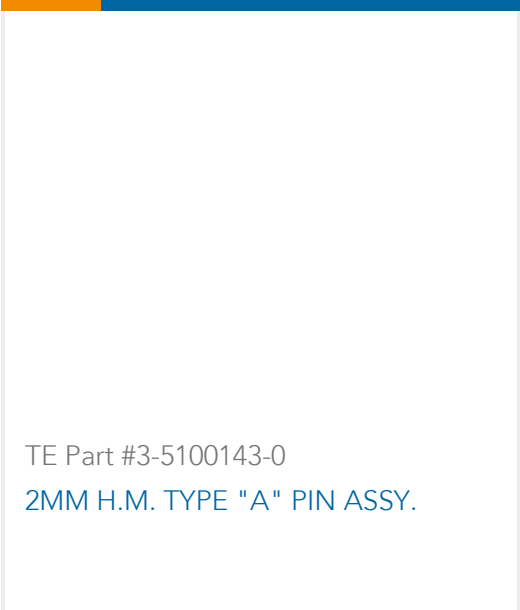


Also in the Series

AMPMODU 50/50 Grid



Customers Also Bought



Documents

Product Drawings

40 50/50 GRID RA HDR LF

English

CAD Files

Customer View Model

ENG\_CVM\_5-104894-4\_J.3d\_igs.zip



English

Customer View Model

[ENG\\_CVM\\_5-104894-4\\_J.3d\\_stp.zip](#)

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Customer View Model

[ENG\\_CVM\\_5-104894-4\\_J.2d\\_dxf.zip](#)

English

3D PDF

English

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Datasheets & Catalog Pages

[AMPMODU\\_INTERCONNECTION\\_SYSTEM\\_SECTION1AND2](#)

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Ribbon Cable Interconnect Solutions

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[Fine Pitch Stacking Connectors - 1.27mm AMPMODU 50/50 Grid Connectors](#)

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Product Specifications

[Application Specification](#)

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Agency Approvals

[UL Report](#)

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